DISCRETE SEMICONDUCTORS



Objective specification File under Discrete Semiconductors, SC09 1996 May 22



### **BGY208**

### FEATURES

- 6.8 V nominal supply voltage
- 3.5 W output power
- Easy output power control by DC voltage.

#### APPLICATIONS

• Digital cellular radio systems with Time Division Multiple Access (TDMA) operation (GSM systems) in the 880 to 915 MHz frequency range.

#### DESCRIPTION

The BGY208 is a three-stage UHF amplifier module in a SOT388A package. The module consists of three NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic substrate.

### PINNING - SOT388A

PIN	DESCRIPTION	
1	RF input	
2	V <sub>C</sub>	
3	Vs	
4	RF output	
Flange	ground	



Fig.1 Simplified outline.

### QUICK REFERENCE DATA

RF performance at  $T_{mb} = 25 \ ^{\circ}C$ .

MODE OF	f	V <sub>S</sub>	V <sub>C</sub>	P <sub>L</sub>	G <sub>p</sub>	η	Z <sub>S</sub> ; Z <sub>L</sub>
OPERATION	(MHz)	(V)	(V)	(W)	(dB)	<b>(%)</b>	(Ω)
Pulsed; $\delta = 1$ : 8	880 to 915	6.8	≤3.5	3.5	≥30.7	typ. 45	

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### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER		MAX.	UNIT
V <sub>S</sub>	DC supply voltage -		8.5	V
V <sub>C</sub>	DC control voltage	_	4	V
PD	input drive power	-	10	mW
PL	load power	_	4	W
T <sub>stg</sub>	storage temperature	-40	+100	°C
T <sub>mb</sub>	operating mounting base temperature	-30	+100	°C

### CHARACTERISTICS

 $Z_S = Z_L = 50 \ \Omega$ ;  $P_D = 3 \ mW$ ;  $V_S = 6.8 \ V$ ;  $V_C \le 3.5 \ V$ ;  $f = 880 \ to 915 \ MHz$ ;  $T_{mb} = 25 \ ^{\circ}C$ ;  $\delta = 1 : 8$ ;  $t_p = 575 \ \mu$ s; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
l <sub>Q</sub>	quiescent current	V <sub>C</sub> = 0.5 V	-	-	100	μA
I <sub>C</sub>	control current	adjust $V_C$ for $P_L = 3.5$ W	-	-	500	μA
PL	load power	V <sub>C</sub> = 3.5 V	3.5	-	-	W
G <sub>p</sub>	power gain	adjust $V_C$ for $P_L = 3.5$ W	30.7	-	-	dB
η	efficiency	adjust $V_C$ for $P_L = 3.5$ W	-	45	-	%
H <sub>2</sub>	second harmonic	adjust $V_C$ for $P_L = 3.5$ W	-	-	-40	dBc
H <sub>3</sub>	third harmonic	adjust $V_C$ for $P_L = 3.5$ W	-	-	-40	dBc
VSWR <sub>in</sub>	input VSWR	adjust $V_C$ for $P_L = 3.5$ W	-	-	3:1	
	stability		-	-	-60	dBc
	isolation	V <sub>C</sub> = 0.5 V	-	-	-36	dBm
	control bandwidth		1	-	-	MHz
P <sub>n</sub>	noise power	P <sub>L</sub> = 3.5 W; bandwidth = 30 kHz; 20 MHz above transmitter band	-	-	-85	dBm
	ruggedness	$V_S$ = 8.5 V; adjust $V_C$ for $P_L$ = 3.5 W VSWR $\leq$ 10 : 1 through all phases	no degradation			

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### SOLDERING

The indicated temperatures are those at the solder interfaces.

Advised solder types are types with a liquidus less than or equal to 210  $^\circ\text{C}.$ 

Solder dots or solder prints must be large enough to wet the contact areas.

Footprints for soldering should cover the module contact area +0.1 mm on all sides.

Soldering can be carried out using a conveyor oven, a hot air oven, an infrared oven or a combination of these ovens.

Hand soldering must be avoided because the soldering iron tip can exceed the maximum permitted temperature of 250  $^{\circ}$ C and damage the module.

The maximum temperature profile and soldering time is indicated as follows (see Fig.2):

- t = 350 s at 100 °C
- t = 300 s at 125 °C
- t = 200 s at 150 °C
- t = 100 s at 175 °C
- t = 50 s at 200  $^{\circ}$ C
- t = 5 s at 250 °C (maximum temperature).

#### Cleaning

The following fluids may be used for cleaning:

- Alcohol
- Bio-Act (Terpene Hydrocarbon)
- Triclean B/S
- Acetone.

Ultrasonic cleaning should not be used since this can cause serious damage to the product.



Fig.2 Maximum allowable temperature profile.

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### PACKAGE OUTLINE



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### DEFINITIONS

Data sheet status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.			
Application information			
Where application information is given, it is advisory and does not form part of the specification.			

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.